

HiPerFRED

 V_{RRM} 1200 V

12 A

40 ns

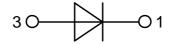
High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DSEP12-12A



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- · Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- · Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-220

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

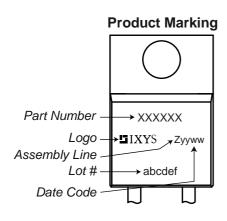
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Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	$T_{VJ} = 25^{\circ}C$			1200	V	
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			100	μΑ
		$V_R = 1200 \text{ V}$	$T_{VJ} = 150$ °C			0.5	mΑ
V _F	forward voltage drop	I _F = 15 A	$T_{VJ} = 25^{\circ}C$			2.62	V
		$I_F = 30 A$				3.19	V
		I _F = 15 A	T _{VJ} = 150°C			1.87	V
		$I_F = 30 A$				2.56	V
I _{FAV}	average forward current	T _c = 135°C	T _{vJ} = 175°C			12	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		T _{VJ} = 175°C			1.03	V
\mathbf{r}_{F}	slope resistance \(\) for power in	oss calculation only				46	mΩ
R _{thJC}	thermal resistance junction to cas	e				1.6	K/W
R _{thCH}	thermal resistance case to heatsin	nk			0.50		K/W
P _{tot}	total power dissipation		$T_{C} = 25^{\circ}C$			95	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			90	Α
C	junction capacitance	$V_R = 600 \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		5		pF
I _{RM}	max. reverse recovery current	<u> </u>	$T_{VJ} = 25 ^{\circ}\text{C}$		6		Α
	($I_F = 15 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 100 ^{\circ}\text{C}$		9		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 15 \text{ A; } V_R = 600 \text{ V} \\ -di_F /dt = 200 \text{ A/} \mu \text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}\text{C}$		40		ns
)	$T_{VJ} = 100 ^{\circ}\text{C}$		140		ns



Package TO-220				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal			35	Α	
T _{vJ}	virtual junction temperature		-55		175	°C	
T _{op}	operation temperature		-55		150	°C	
T _{stg}	storage temperature		-55		150	°C	
Weight				2		g	
M _D	mounting torque		0.4		0.6	Nm	
F_c	mounting force with clip		20		60	N	



Ord	dering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Sta	andard	DSEP12-12A	DSEP12-12A	Tube	50	470465

Similar Part	Package	Voltage class
DSEP12-12B	TO-220AC (2)	1200
DSEP15-12CR	ISOPLUS247 (2)	1200

Equiva	alent Circuits for	Simulation	* on die level	T _{VJ} = 175 °C
$I \rightarrow V_0$)— <u>R</u> o	Fast Diode		
V _{0 max}	threshold voltage	1.03		V
$R_{0 \text{ max}}$	slope resistance *	43		mΩ

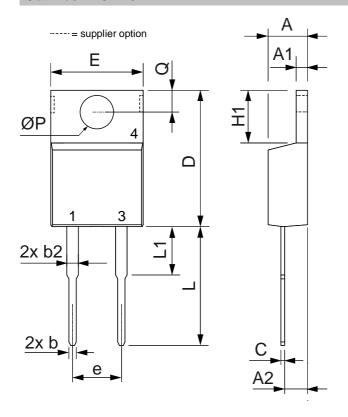
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Outlines TO-220



Dim.	Millimeter		Inches		
	Min.	Max.	Min.	Max.	
Α	4.32	4.82	0.170	0.190	
A1	1.14	1.39	0.045	0.055	
A2	2.29	2.79	0.090	0.110	
b	0.64	1.01	0.025	0.040	
b2	1.15	1.65	0.045	0.065	
С	0.35	0.56	0.014	0.022	
D	14.73	16.00	0.580	0.630	
Е	9.91	10.66	0.390	0.420	
е	5.08	BSC	0.200	BSC	
H1	5.85	6.85	0.230	0.270	
L	12.70	13.97	0.500	0.550	
L1	2.79	5.84	0.110	0.230	
ØP	3.54	4.08	0.139	0.161	
Q	2.54	3.18	0.100	0.125	





Fast Diode

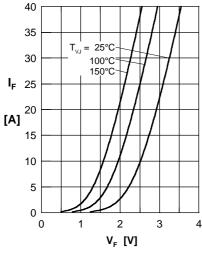


Fig. 1 Forward current I_F versus V_F

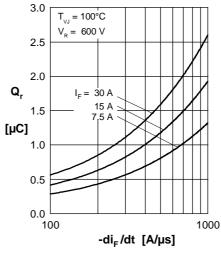


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

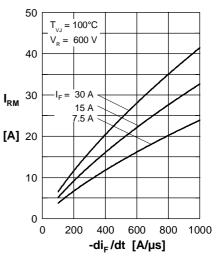


Fig. 3 Typ. peak reverse current $I_{\rm RM}$ versus $-{\rm di_F}/{\rm dt}$

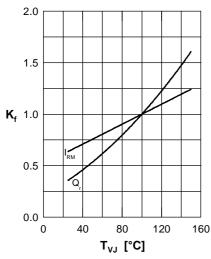


Fig. 4 Dynamic parameters Q_r , I_{RM} versus T_{VJ}

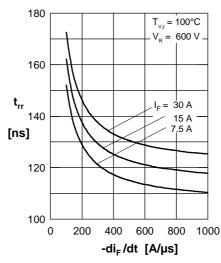


Fig. 5 Typ. recovery time t_{rr} versus -di_F/dt

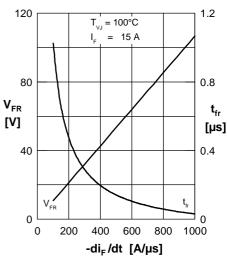


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

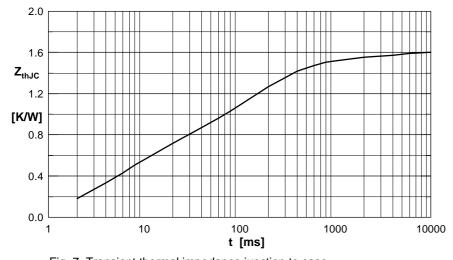


Fig. 7 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t _i (s)
1	0.160	0.0010
2	0.100	0.0150
3	0.500	0.0040
4	0.840	0.1200

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单击下面可查看定价,库存,交付和生命周期等信息

>>Littelfuse(美国力特)